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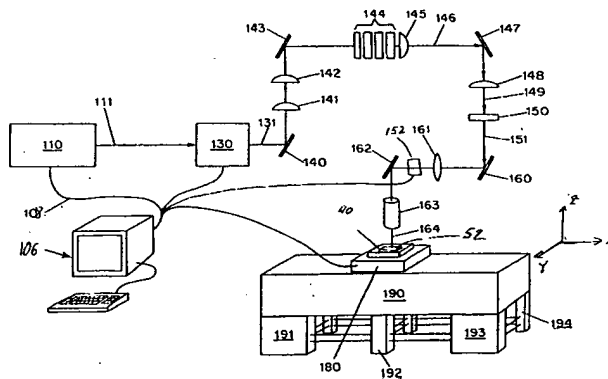
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(54) Title: METHOD AND APPARATUS FOR PROCESSING THIN METAL LAYERS



(57) Abstract: A method and apparatus for processing a thin metal layer on a substrate to control the grain size, grain shape, and grain boundary location and orientation in the metal layer by irradiating the metal layer with a first excimer laser pulse having an intensity pattern defined by a mask to have shadow regions and beamlets. Each region of the metal layer overlapped by a beamlet is melted throughout its entire thickness, and each region of the metal layer overlapped by a shadow region remains at least partially unmelted. Each at least partially unmelted region adjoins adjacent melted regions. After irradiation by the first excimer laser pulse, the melted regions of the metal layer are permitted to resolidify. During resolidification, the at least partially unmelted regions seed growth of grains in adjoining melted regions to produce larger grains. After completion of resolidification of the melted regions following irradiation by the first excimer laser pulse, the metal layer is irradiated by a second excimer laser pulse having a shifted intensity pattern so that the shadow regions overlap regions of the metal layer having fewer and larger grains. Each region of the metal layer overlapped by one of the shifted beamlets is melted throughout its entire thickness, while each region of the metal layer overlapped by one of the shifted shadow regions remains at least partially unmelted. During resolidification of the melted regions after irradiation by the second radiation beam pulse, the larger grains in the at least partially unmelted regions seed growth of even larger grains in adjoining melted regions. The irradiation, resolidification and re-irradiation of the metal layer may be repeated, as needed, until a desired grain structure is obtained in the metal layer.

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INTERNATIONAL SEARCH REPORT

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A. CLASSIFICATION OF SUBJECT MATTER
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According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)

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Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practical, search terms used)

EPO-Internal, INSPEC, PAJ

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category *	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	HAU-RIEGE C S ET AL: "The effects of microstructural transitions at width transitions on interconnect reliability" JOURNAL OF APPLIED PHYSICS, 15 JUNE 2000, AIP, USA, vol. 87, no. 12, pages 8467-8472, XP002200743 ISSN: 0021-8979 the whole document --- -/-	1

☒ Further documents are listed in the continuation of box C.☒ Patent family members are listed in annex.

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International Application No

PCT/US 01/31391

C.(Continuation) DOCUMENTS CONSIDERED TO BE RELEVANT

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X	<p>MCWILLIAMS B M ET AL: "WAFER-SCALE LASER PANTOGRAPHY: FABRICATION OF N-METAL-OXIDE-SEMICONDUCTOR TRANSISTORS AND SMALL-SCALE INTEGRATED CIRCUITS BY DIRECT-WRITE LASER-INDUCED PYROLYTIC REACTIONS"</p> <p>APPLIED PHYSICS LETTERS, AMERICAN INSTITUTE OF PHYSICS. NEW YORK, US, vol. 43, no. 10, November 1983 (1983-11), pages 946-948, XP000816966</p> <p>ISSN: 0003-6951</p> <p>figure 1</p>	68
X	<p>MARIUCCI L ET AL: "Grain boundary location control by patterned metal film in excimer laser crystallized polysilicon"</p> <p>PROCEEDINGS OF THE FIFTH INTERNATIONAL CONFERENCE ON POLYCRYSTALLINE SEMICONDUCTORS (POLYSE '98), SCHWABISCH GMUND, GERMANY, 13-18 SEPT. 1998, vol. 67-68, pages 175-180, XP008004041</p> <p>Diffusion and Defect Data Part B (Solid State Phenomena), 1999, Balaban Publishers; Scitec Publications, Switzerland</p> <p>ISSN: 1012-0394</p> <p>the whole document</p>	1
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A	<p>US 6 014 944 A (RUSSELL STEPHEN D ET AL)</p> <p>18 January 2000 (2000-01-18)</p> <p>the whole document</p>	

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International Application No

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C.(Continuation) DOCUMENTS CONSIDERED TO BE RELEVANT

Category *	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
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INTERNATIONAL SEARCH REPORT
Information on patent family members

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